

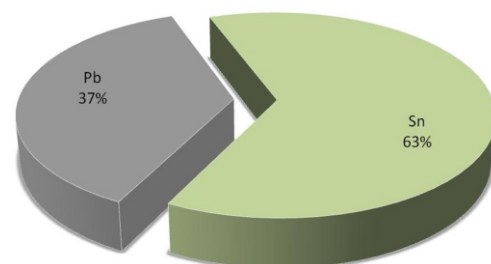


Alloy

Tin Lead

NANOPARTICLES

Tin Lead Alloy Nanoparticles



Composition Chart

Sn:Pb

Stock No:
NS6130-07-720

CAS	:	7440-31-5 / 7439-92-1
Purity	:	99.9%
APS	:	<80nm
Color	:	Silver Metallic
Form	:	Powder

Technical Specification

Molecular Formula	:	Sn:Pb
Specific Gravity	:	8.60g/cm ³
Melting Point	:	183°C

Chemical Composition

Assay	:	99.9%
Sn	:	63%
Pb	:	37%

Tin/lead (Sn/Pb) solders have long been used as electrical interconnect in most areas of electronic packaging. Lead, one of the components in solders, has been recognized as health threat to human beings and natural environment. Alloys that combine tin and lead have a number of different names and applications. Solder is an alloy of tin and lead used to create electrical joints. Tin/Silver solders are used for high temperature, high reliability interconnect applications. Solder joints using Tin/Silver alloys maintain better high temperature strength than tin/lead solders.

Application:

- ✓ Used to create electrical joints
- ✓ Electronic assembly
- ✓ Die attachments
- ✓ Thick films
- ✓ Soldering applications

ISO 9001:2015
CERTIFIED COMPANY



20ZICE4589C



19ZAZGO1274G



20ZICE4588M



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